

Cheng-Hui Lin

List of Publications by Year in descending order

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5
papers

8
citations

2682572

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2917675

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docs citations

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citing authors

#	ARTICLE	IF	CITATIONS
1	Mechanically Compliant Thermal Interfaces Using Biporous Copper-Polydimethylsiloxane Interpenetrating Phase Composite. <i>Advanced Materials Interfaces</i> , 2021, 8, .	3.7	5
2	The evolution from surface-to bubble dynamics-dominant growth mechanisms of synchronized bubble-templated microporous copper. <i>Material Design and Processing Communications</i> , 2021, 3, e229.	0.9	0
3	Microflow-Enhanced Bubble Dynamics Along With Gradient Porous Surfaces. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2021, 143, .	1.8	0
4	Pressure-Dependent Thermal Characterization of Biporous Copper Structures. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2020, 10, 568-576.	2.5	3
5	Pressure-Dependent Thermal Characterization of Bi-Porous Copper Structures. , 2019, , .		0